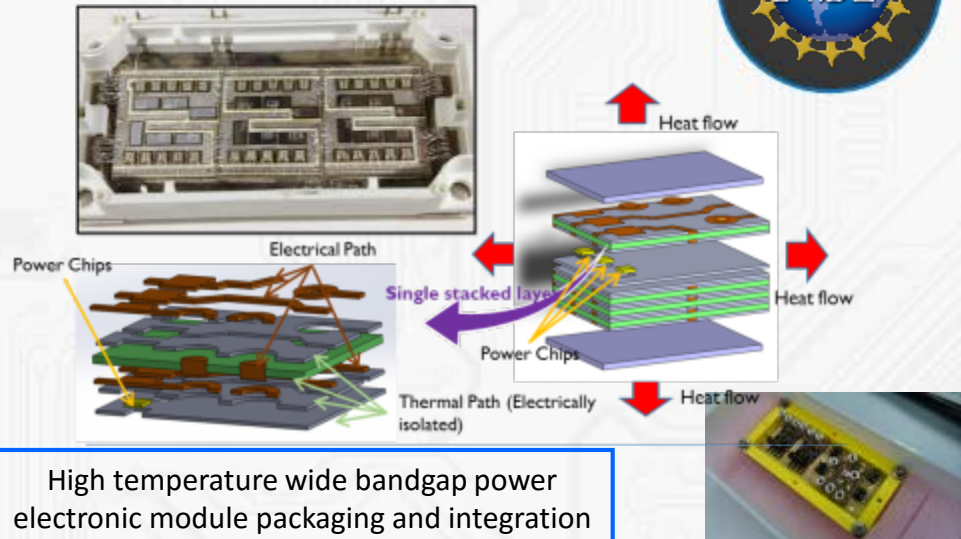


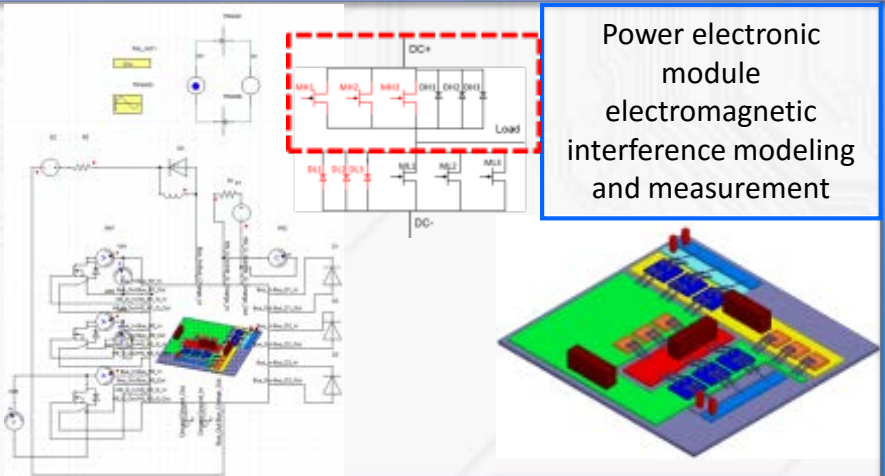


- High temperature wide bandgap power electronic module packaging and integration
- Passives and module packaging materials
- Power electronic module electromagnetic interference (EMI) modeling and measurement

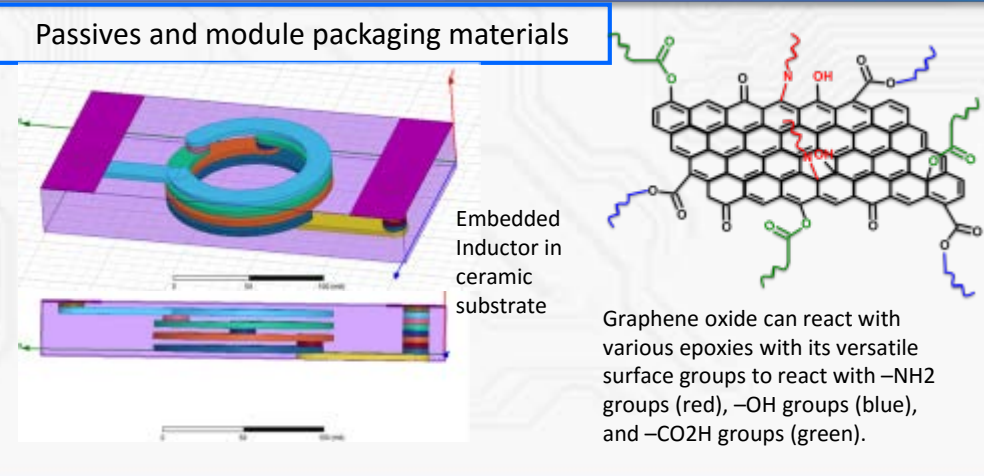
<http://electrical-engineering.uark.edu/directory/profile.php?uld=siang>



High temperature wide bandgap power electronic module packaging and integration



Power electronic module electromagnetic interference modeling and measurement



Passives and module packaging materials

Embedded Inductor in ceramic substrate

Graphene oxide can react with various epoxies with its versatile surface groups to react with $-NH_2$ groups (red), $-OH$ groups (blue), and $-CO_2H$ groups (green).